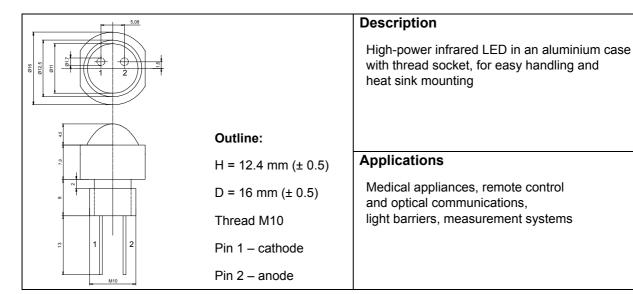
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Radiation	Туре	Technology	Case	
Infrared	4 W	AlGaAs/GaAlAs	Plastic lens, metal case	



Absolute Maximum Ratings

at T_{amb} = 25°C, on heat sink (S \geq 200 cm²), unless otherwise specified

Parameter	Test conditions	Symbol	Value	Unit
DC forward current	on heat sink		1.5	А
Peak forward current	t _p ≤10 μs, f≤500 Hz		2,0	А
Power dissipation	on heat sink	Р	4	W
Operating temperature range	on heat sink	T _{amb}	-25 to +100	°C
Storage temperature range	on heat sink	T _{stg}	-25 to +100	°C
Junction temperature	on heat sink	T _j	100	°C

Electrical Characteristics

 T_{amb} = 25°C, unless otherwise specified

Parameter	Test conditions	Symbol	Min	Тур	Max	Unit
Forward voltage	I _F = 350 mA	V_{F}		1.6	1.9	V
Forward voltage*	I _F = 1000 mA	V_{F}		2.0	2.3	٧
Switching time	I _F = 350 mA	t _r , t _f		10/22		ns
Reverse voltage	I _R = 10 μA	V _R	5			
Thermal resistance junction-case		R_{thJC}		10		K/W

^{*}only recommended on optimal heat sink

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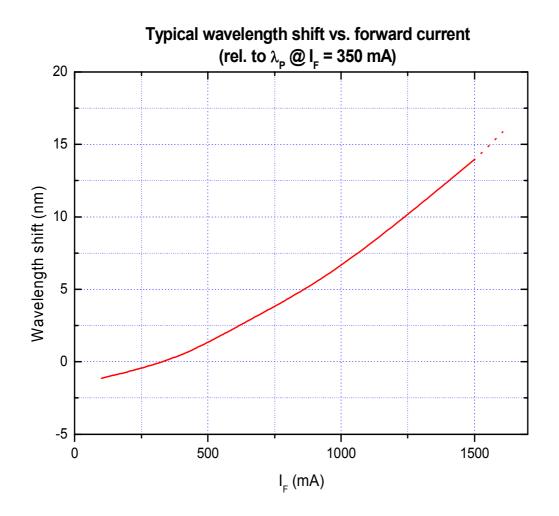
Optical Characteristics

at T_{amb} = 25°C, on heat sink (S \geq 200 cm²), unless otherwise specified

Parameter	Test conditions	Symbol	Min	Тур	Max	Unit
Radiant power	I _F = 350 mA	Φ_{e}	70	90		mW
Radiant power*	I _F = 1000 mA	Φ_{e}		240		mW
Radiant intensity	I _F = 350 mA	I_{e}		210		mW/sr
Radiant intensity*	I _F = 1000 mA	I _e		615		mW/sr
Peak wavelength	I _F = 350 mA	λ_{p}	860	870	880	nm
Spectral bandwidth at 50%	I _F = 350 mA	$\Delta\lambda_{0.5}$		42		nm
Viewing angle	I _F = 350 mA	φ		35		deg

^{*}only recommended on optimal heat sink

Note: All measurements carried out with *EPIGAP* equipment, on blank aluminium heat sink, S = 180 cm², passive cooling. Measurement results and curve characteristics obtained with other heat sinks may differ.

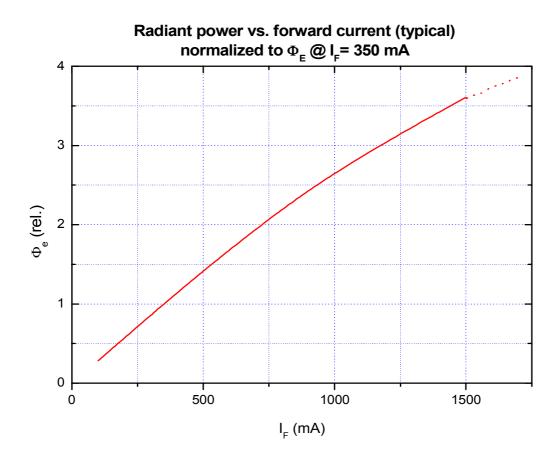


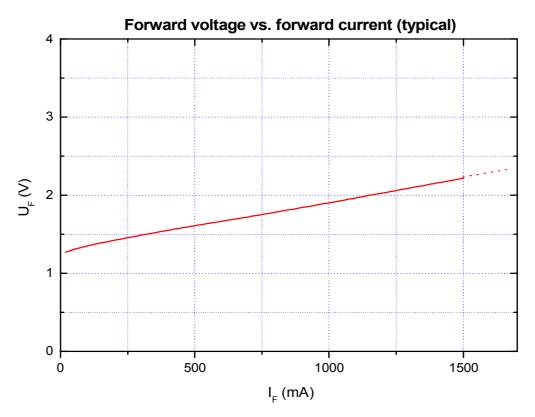
We reserve the right to make changes to improve technical design and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer.

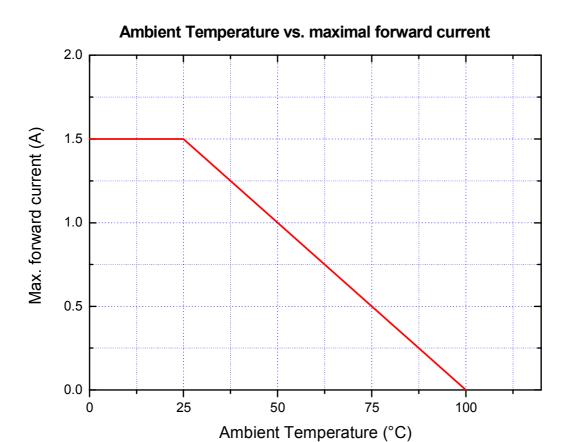
EPIGAP Optoelektronik GmbH, D-12555 Berlin, Köpenicker Str. 325 b, Haus 201

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Remarks concerning optical radiation safety*

At low forward current (<250 mA), and continuous operation, this LED may be classified as LED product *Class 1*, according to standard IEC 60825-1:A2. *Class 1* products are safe to eyes and skin under reasonably predictable conditions. This implicates a direct observation of the light beam by means of optical instruments.

When driven with higher continuous forward current, (up to max. DC current), this product should be classified as LED product *Class 1M*, according to standard IEC 60825-1:A2. *Class 1M* products are safe to eyes and skin under normal conditions, including when users view the light beam directly. *Class 1M* products produce either a highly divergent beam or a large diameter beam. Therefore only a small part of the whole light beam can enter the eye. However, such optical products can be harmful to the retina if the beam is viewed using magnifying optical instruments. Therefore, users should not incorporate optics that could concentrate the output into the eyes.

*Note: Safety classification of an optical component mainly depends on the intended application and the way the component is being used. Furthermore, all statements made to classification are based on calculations and are only valid for this LED "as it is", and at continuous operation. Using pulsed current or altering the light beam with additional optics may lead to different safety classifications. Therefore these remarks should be taken as recommendation and guideline only.

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Handling precautions

To prevent damage to the LED during soldering and assembly, following precautions have to be taken into account.

a) The bending point of the lead frame should be located at least 2.5 mm away from the body.



c) To ensure an adequate strain relief, the lead frames have to be firmly fixed during soldering.



e) LEDs are static sensitive devices, so adequate handling precautions have to be taken, e.g. wearing grounding wrist straps.



b) While bending, the base of the lead frame has to be fixed with radio pliers or similar.



d) Avoid any torsion or tensile loading of the lead frames, especially when they have been heated after being soldered.

